

### General Description

The MDHT4N20Y uses advanced Magnachip's MOSFET Technology, which provides low on-state resistance, high switching performance and excellent quality.

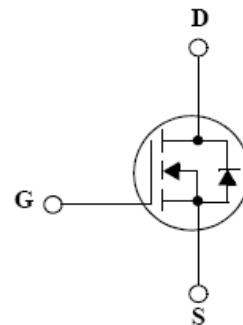
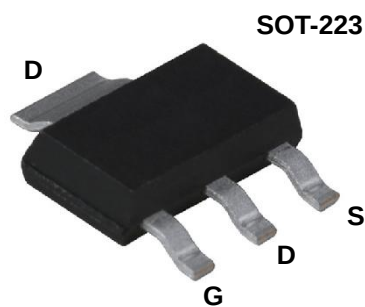
MDHT4N20Y is suitable device for LED TV and general purpose applications.

### Features

- $V_{DS} = 200V$
  - $I_D = 0.85A$
  - $R_{DS(ON)} \leq 1.35\Omega$
- @  $V_{GS} = 10V$   
@  $V_{GS} = 10V$

### Applications

- Power Supply
- PFC
- LED TV



### Absolute Maximum Ratings ( $T_a = 25^\circ C$ )

| Characteristics                                  |                           | Symbol         | Rating   | Unit          |
|--------------------------------------------------|---------------------------|----------------|----------|---------------|
| Drain-Source Voltage                             |                           | $V_{DSS}$      | 200      | V             |
| Gate-Source Voltage                              |                           | $V_{GSS}$      | $\pm 20$ | V             |
| Continuous Drain Current                         | $T_C = 25^\circ C$        | $I_D$          | 0.85     | A             |
|                                                  | $T_C = 100^\circ C$       |                | 0.54     | A             |
| Pulsed Drain Current <sup>(1)</sup>              |                           | $I_{DM}$       | 3.4      | A             |
| Power Dissipation                                | $T_C = 25^\circ C$        | $P_D$          | 2.1      | W             |
|                                                  | Derate above $25^\circ C$ |                | 0.017    | W/ $^\circ C$ |
| Peak Diode Recovery $dv/dt$ <sup>(3)</sup>       |                           | $Dv/dt$        | 5.5      | V/ns          |
| Repetitive Pulse Avalanche Energy <sup>(4)</sup> |                           | $E_{AR}$       | 0.21     | mJ            |
| Avalanche current <sup>(1)</sup>                 |                           | $I_{AR}$       | 0.85     | A             |
| Single Pulse Avalanche Energy <sup>(4)</sup>     |                           | $E_{AS}$       | 52       | mJ            |
| Junction and Storage Temperature Range           |                           | $T_J, T_{stg}$ | -55~150  | $^\circ C$    |

### Thermal Characteristics

| Characteristics                           | Symbol          | Rating | Unit         |
|-------------------------------------------|-----------------|--------|--------------|
| Thermal Resistance, Junction-to-Ambient * | $R_{\theta JA}$ | 60     | $^\circ C/W$ |

\* When mounted on the minimum pad size recommended (PCM Mount)

## Ordering Information

| Part Number  | Temp. Range | Package | Packing       | RoHS Status  |
|--------------|-------------|---------|---------------|--------------|
| MDHT4N20YURH | -55~150°C   | SOT-223 | Reel and Tape | Halogen Free |

## Electrical Characteristics (Ta =25°C)

| Characteristics                                          | Symbol              | Test Condition                                                                            | Min | Typ  | Max  | Unit |
|----------------------------------------------------------|---------------------|-------------------------------------------------------------------------------------------|-----|------|------|------|
| Static Characteristics                                   |                     |                                                                                           |     |      |      |      |
| Drain-Source Breakdown Voltage                           | BV <sub>DSS</sub>   | I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V                                              | 200 | -    | -    | V    |
| Gate Threshold Voltage                                   | V <sub>GS(th)</sub> | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA                                | 1.0 | -    | 2.0  |      |
| Drain Cut-Off Current                                    | I <sub>DSS</sub>    | V <sub>DS</sub> = 200V, V <sub>GS</sub> = 0V                                              | -   | -    | 1    | μA   |
| Gate Leakage Current                                     | I <sub>GSS</sub>    | V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V                                              | -   | -    | 100  | nA   |
| Drain-Source ON Resistance                               | R <sub>DS(ON)</sub> | V <sub>GS</sub> = 10V, I <sub>D</sub> = 0.425A                                            | -   | 1.1  | 1.35 | Ω    |
| Forward Transconductance                                 | g <sub>fs</sub>     | V <sub>DS</sub> = 30V, I <sub>D</sub> = 0.425A                                            | -   | 1.3  | -    | S    |
| Dynamic Characteristics                                  |                     |                                                                                           |     |      |      |      |
| Total Gate Charge                                        | Q <sub>g</sub>      | V <sub>DS</sub> = 160V, I <sub>D</sub> = 3.8A, V <sub>GS</sub> = 5V                       | -   | 3.2  | -    | nC   |
| Gate-Source Charge                                       | Q <sub>gs</sub>     |                                                                                           | -   | 0.64 | -    |      |
| Gate-Drain Charge                                        | Q <sub>gd</sub>     |                                                                                           | -   | 1.6  | -    |      |
| Input Capacitance                                        | C <sub>iss</sub>    | V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1.0MHz                                   | -   | 148  | -    | pF   |
| Reverse Transfer Capacitance                             | C <sub>rss</sub>    |                                                                                           | -   | 11.3 | -    |      |
| Output Capacitance                                       | C <sub>oss</sub>    |                                                                                           | -   | 42.7 | -    |      |
| Turn-On Delay Time                                       | t <sub>d(on)</sub>  | V <sub>GS</sub> = 5V, V <sub>DS</sub> = 100V, I <sub>D</sub> = 3.8A, R <sub>G</sub> = 25Ω | -   | 6    | -    | ns   |
| Rise Time                                                | t <sub>r</sub>      |                                                                                           | -   | 38   | -    |      |
| Turn-Off Delay Time                                      | t <sub>d(off)</sub> |                                                                                           | -   | 11   | -    |      |
| Fall Time                                                | t <sub>f</sub>      |                                                                                           | -   | 13   | -    |      |
| Drain-Source Body Diode Characteristics                  |                     |                                                                                           |     |      |      |      |
| Maximum Continuous Drain to Source Diode Forward Current | I <sub>S</sub>      |                                                                                           | -   | 0.85 | -    | A    |
| Source-Drain Diode Forward Voltage                       | V <sub>SD</sub>     | I <sub>S</sub> = 0.85A, V <sub>GS</sub> = 0V                                              | -   | -    | 1.5  | V    |
| Body Diode Reverse Recovery Time                         | t <sub>rr</sub>     | I <sub>F</sub> = 3.8A, dI/dt = 100A/μs <sup>(3)</sup>                                     | -   | 90   | -    | ns   |
| Body Diode Reverse Recovery Charge                       | Q <sub>rr</sub>     |                                                                                           | -   | 0.24 | -    | μC   |

Note :

1. Pulse width is based on  $R_{\theta JC}$  &  $R_{\theta JA}$  and the maximum allowed junction temperature of 150°C.
2. Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ , pulse width limited by junction temperature  $T_{J(MAX)} = 150^\circ C$ .
3.  $I_{SD} \leq 3.8A$ ,  $di/dt \leq 300A/\mu s$ ,  $V_{DD} \leq BV_{DSS}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ C$
4.  $L = 108mH$ ,  $I_{AS} = 0.85A$ ,  $V_{DD} = 50V$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ C$

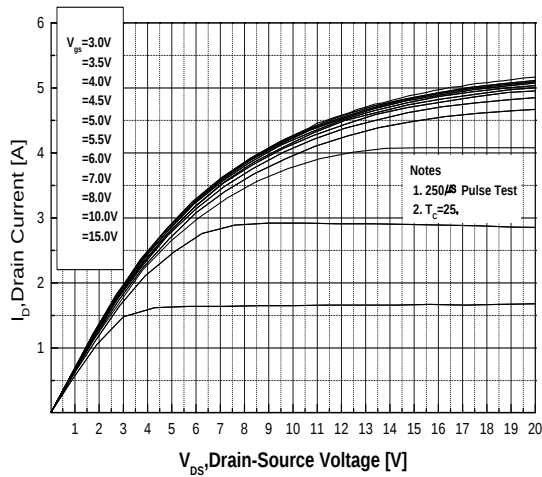


Fig.1 On-Region Characteristics

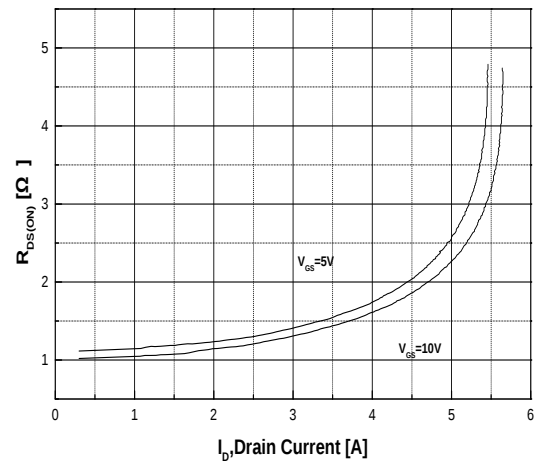


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

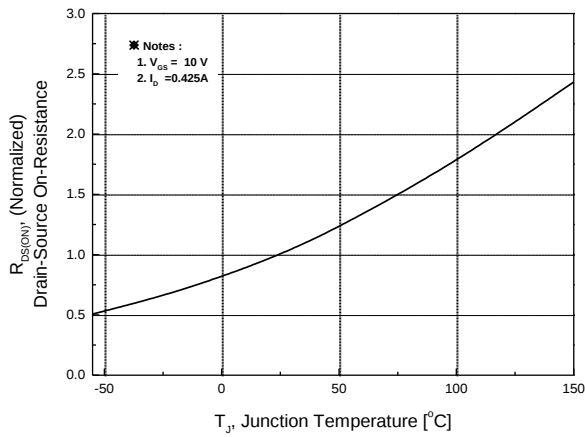


Fig.3 On-Resistance Variation with Temperature

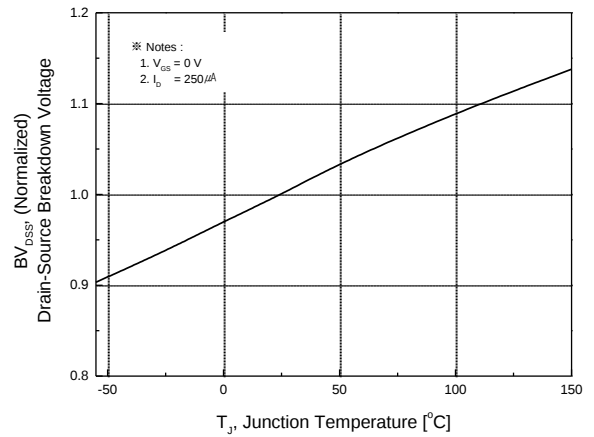


Fig.4 Breakdown Voltage Variation vs. Temperature

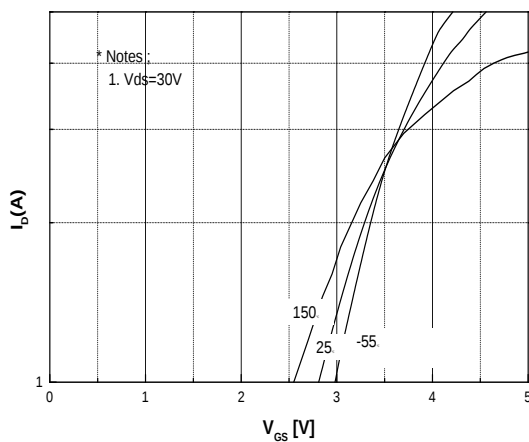


Fig.5 Transfer Characteristics

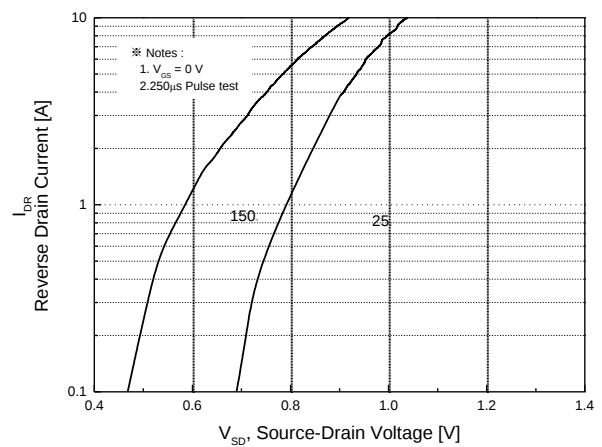
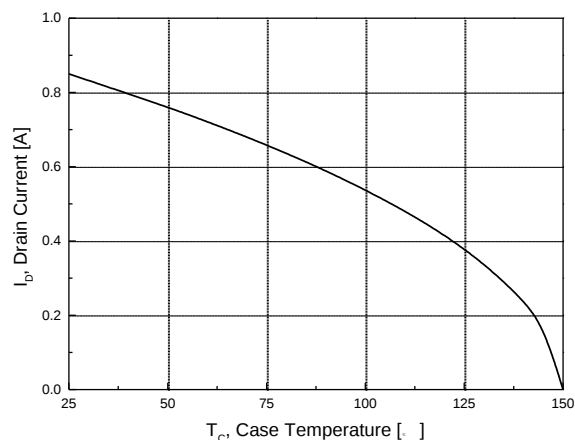
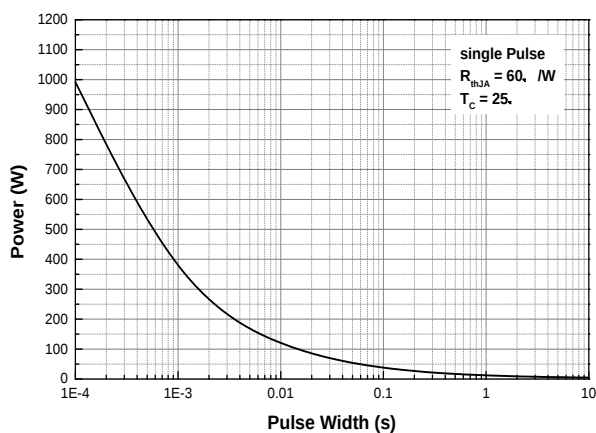
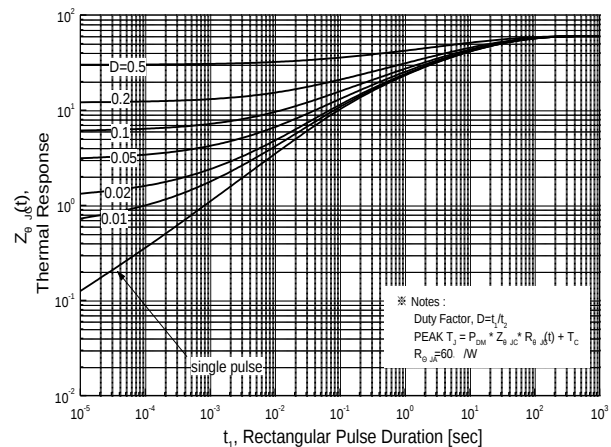
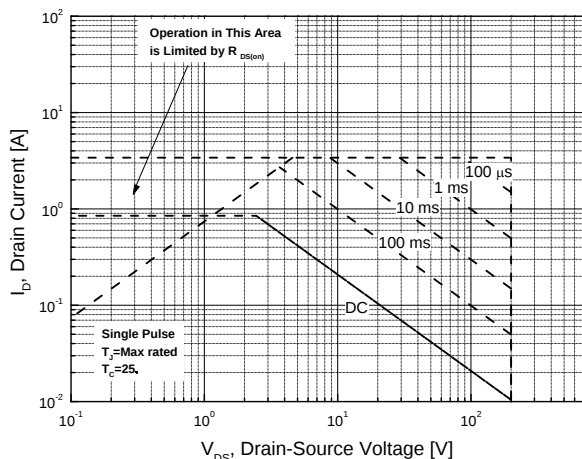
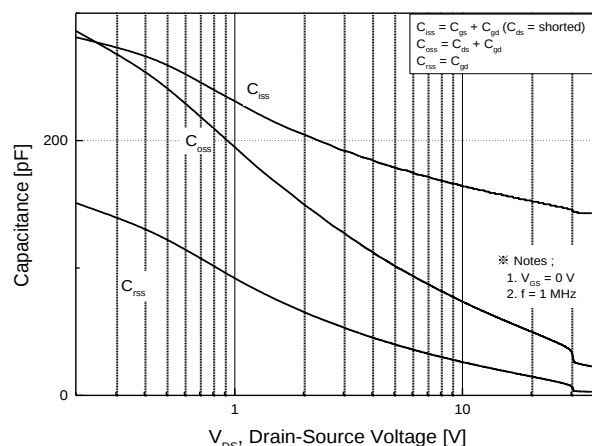
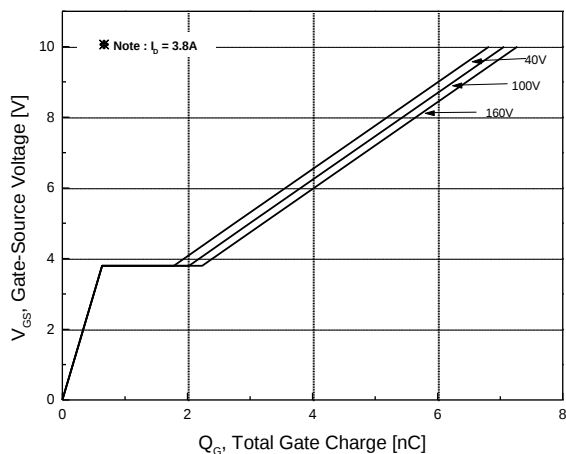


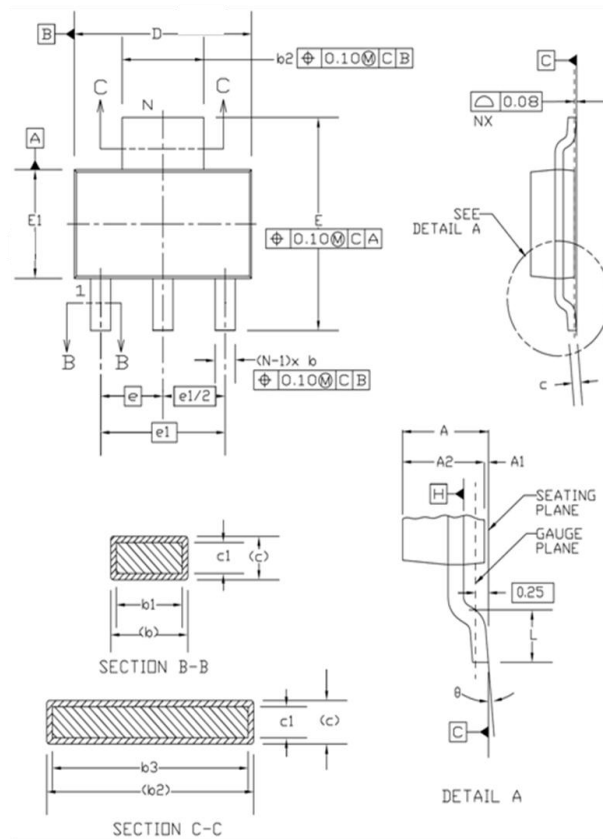
Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature



# Physical Dimension

## SOT-223

Dimensions are in millimeters, unless otherwise specified



| Symbol | Min        | Nom | Max  |
|--------|------------|-----|------|
| A      | -          | -   | 1.80 |
| A1     | 0.00       | -   | 0.10 |
| A2     | 1.50       | -   | 1.70 |
| b      | 0.60       | -   | 0.84 |
| b1     | 0.60       | -   | 0.79 |
| b2     | 2.90       | -   | 3.10 |
| b3     | 2.84       | -   | 3.05 |
| c      | 0.23       | -   | 0.35 |
| c1     | 0.23       | -   | 0.33 |
| D      | 6.20       | -   | 6.70 |
| E      | 6.70       | -   | 7.30 |
| E1     | 3.30       | -   | 3.70 |
| e      | 2.30 BASIC |     |      |
| e1     | 4.60 BASIC |     |      |
| L      | 0.75       | -   | -    |
| θ      | 0°         | -   | 10°  |

**DISCLAIMER:**

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